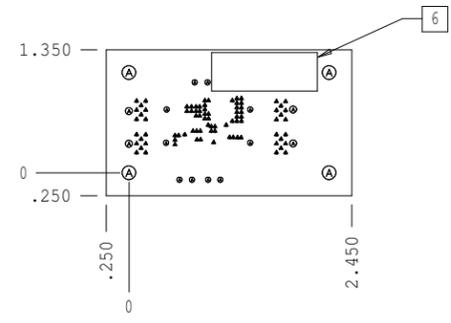
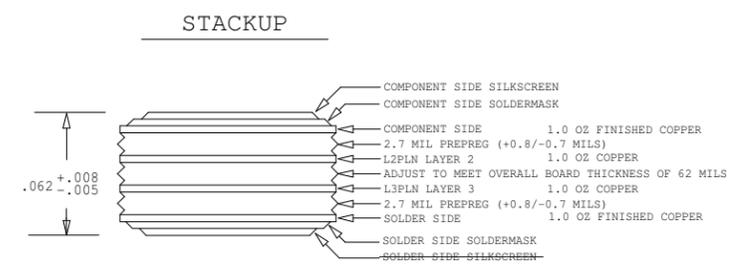


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

- NOTES:
- PRINTED CIRCUIT BOARD IS SHOWN VIEWED FROM COMPONENT SIDE.
 - ALL MATERIALS TO BE ROHS COMPLIANT. FABRICATE PER IPC-6012 AND IPC-6011. INSPECT TO IPC-A-600.
 - BOARD MATERIAL: ROHS COMPLIANT FR-4, LAMINATED SHEET, HTE COPPER CLAD, TYPE GF/GFG, WOVEN GLASS BASE, FLAME RESISTANT, MEETING UL-94V0 OR BETTER. Tg RATING OF 130 DEGREES C OR GREATER. Td RATING OF 340 DEGREES C OR GREATER MATERIAL IN ACCORDANCE WITH IPC-4101.
BONDING MATERIAL: ROHS COMPLIANT PLASTIC SHEET, TYPE GF/GFG BASE MATERIAL, GLASS BASE PRE-IMPREGNATED (B-STAGE). Tg RATING 130 C OR GREATER. Td RATING OF 340 DEGREES C OR GREATER MATERIAL IN ACCORDANCE WITH IPC-4101. THIS BOARD HAS 4 LAYERS.
 - FINISH;
 - PLATED HOLES SHALL HAVE A MINIMUM COPPER THICKNESS OF .0008 IN. AND HAVE A MINIMUM OF 80% COVERAGE.
 - LPI SOLDERMASK PER IPC-SM-840 OVER BARE COPPER (SMOBC). SOLDERMASK REGISTRATION TO BE WITHIN +/- .003 OF IT'S RESPECTIVE CIRCUIT LAYER, NO MASK ON PADS.
 - PLATING TO BE ROHS COMPLIANT, IMMERSION SILVER, PER IPC-4553.
 - HOLE DIMENSIONS APPLY AFTER FINISHING.
 - HOLE TOLERANCE; +/- .003 PLATED AND +/- .005 NON-PLATED. HOLES .018 AND UNDER MAY BE PLUGGED.
 - SILKSCREEN WITH ROHS COMPLIANT WHITE NON-CONDUCTIVE INK, NO INK ON PADS.
 - UL RECOGNIZED VENDOR MARK AND 94V-0 TO APPEAR ON SOLDERSIDE IN ETCH APPROXIMATELY WHERE SHOWN. ROHS COMPLIANT WHITE NON-CONDUCTIVE INK OR LASER MARKING. ROHS COMPLIANT SYMBOL TO APPEAR ON SOLDERSIDE IN ROHS COMPLIANT WHITE NON-CONDUCTIVE INK ONLY.
 - WARP AND TWIST NOT TO EXCEED .010 IN./IN.
 - FOR COPPER WEIGHT AND BOARD THICKNESS SEE STACKUP DETAIL.
 - LAYER TO LAYER REGISTRATION .005 IN.
 - ~~CONTROLLED IMPEDANCE 60 OHMS +/-15%.~~



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
▲	14.0	PLATED	85
•	63.0	PLATED	10
⊙	81.0	PLATED	4
Ⓐ	156.0	NON-PLATED	4



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- .005 3 PL DECIMALS +/- .015 ANGLES +/- 1.0 DEGREE FRACTIONS +/-	SIGNATURES	DATE	ON Semiconductor USE PURSUANT TO COMPANY INSTRUCTIONS NCP1599 EVALUATION BOARD FABRICATION DRAWING
	DRAWN XXX	05/18/10	
	CHECKED		
	ENGRG		
ISSUED			
SIZE D	FSCM NO	DWG NO	NCP1599GEVB REV P3
SCALE 1/1			SHEET 1 OF 1